BT137S-800E

4Q Triac

Rev. 3 — 30 March 2011 Product data sheet

1. Product profile

1.1 General description

Planar passivated sensitive gate four quadrant triac in a SOT428 (DPAK) surface-mountable plastic package intended for use in general purpose bidirectional switching and phase control applications. This sensitive gate "series E" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

1.2 Features and benefits

- Direct triggering from low power drivers and logic ICs
- High blocking voltage capability
- Low holding current for low current loads and lowest EMI at commutation
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate
- Surface-mountable package
- Triggering in all four quadrants

1.3 Applications

- General purpose motor control
- General purpose switching

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	-	800	V
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; see Figure 4; see Figure 5	-	-	65	A
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq$ 102 °C; see Figure 1; see Figure 2; see Figure 3	-	-	8	A

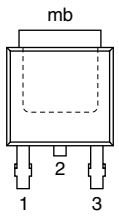
Table 1. Quick reference data *...continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T2+ G+; T_j = 25 °C; see Figure 7	-	2.5	10	mA
		V_D = 12 V; I_T = 0.1 A; T2+ G-; T_j = 25 °C; see Figure 7	-	4	10	mA
		V_D = 12 V; I_T = 0.1 A; T2- G-; T_j = 25 °C; see Figure 7	-	5	10	mA
		V_D = 12 V; I_T = 0.1 A; T2- G+; T_j = 25 °C; see Figure 7	-	11	25	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; see Figure 9	-	2.5	20	mA

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		



SOT428 (DPAK)

sym051

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BT137S-800E	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102$ °C; see Figure 1; see Figure 2; see Figure 3	-	8	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25$ °C; $t_p = 20$ ms; see Figure 4; see Figure 5	-	65	A
		full sine wave; $T_{j(init)} = 25$ °C; $t_p = 16.7$ ms	-	71	A
I^2t	I^2t for fusing	$t_p = 10$ ms; sine-wave pulse	-	21	A^2s
dI_T/dt	rate of rise of on-state current	$I_T = 12$ A; $I_G = 0.2$ A; $dI_G/dt = 0.2$ A/µs; T2+ G+	-	50	A/µs
		$I_T = 12$ A; $I_G = 0.2$ A; $dI_G/dt = 0.2$ A/µs; T2+ G-	-	50	A/µs
		$I_T = 12$ A; $I_G = 0.2$ A; $dI_G/dt = 0.2$ A/µs; T2- G-	-	50	A/µs
		$I_T = 12$ A; $I_G = 0.2$ A; $dI_G/dt = 0.2$ A/µs; T2- G+	-	10	A/µs
I_{GM}	peak gate current		-	2	A
V_{GM}	peak gate voltage		-	5	V
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T_{stg}	storage temperature		-40	150	°C
T_j	junction temperature		-	125	°C

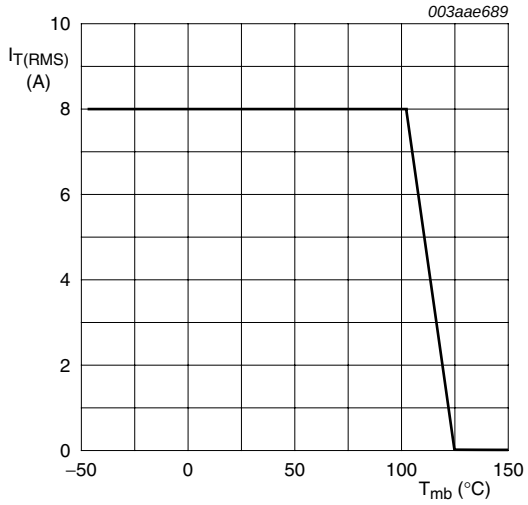
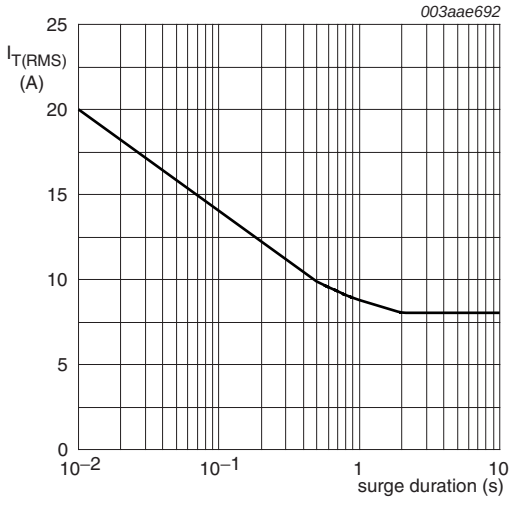


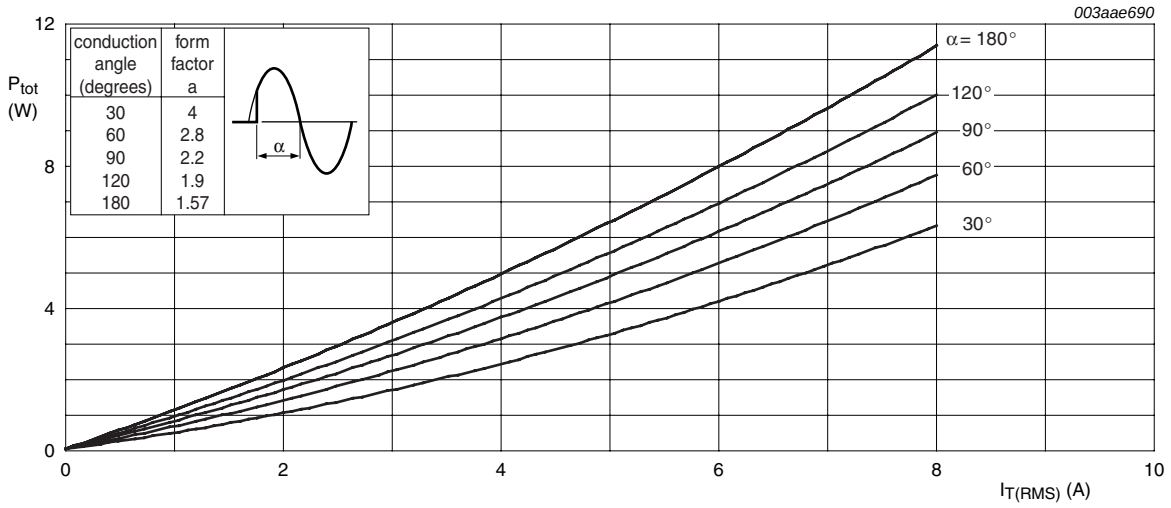
Fig 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz

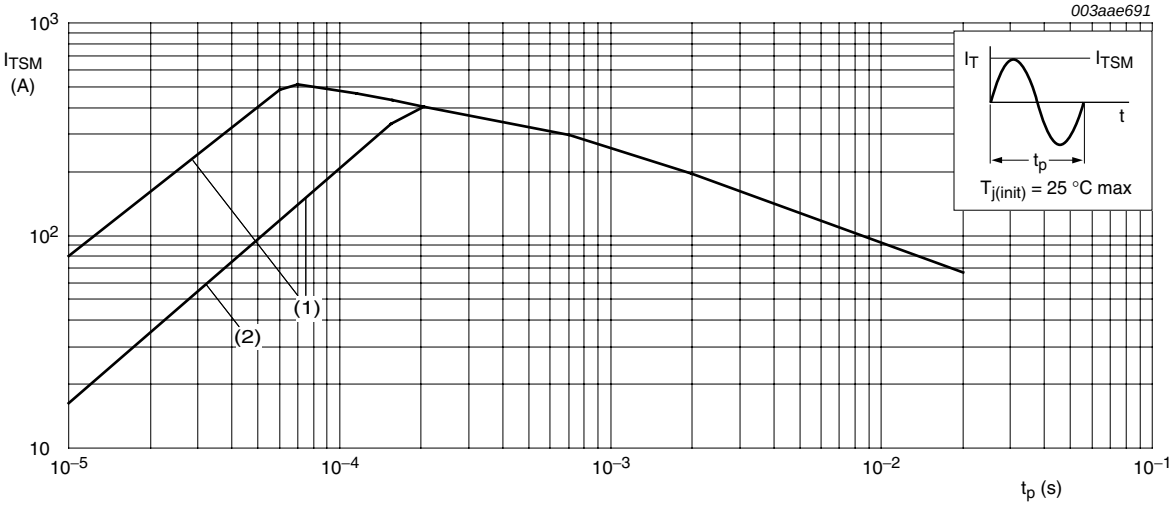
$T_{mb} \leq 102$ °C

Fig 2. RMS on-state current as a function of surge duration; maximum values



α = conduction angle

Fig 3. Total power dissipation as a function of RMS on-state current; maximum values

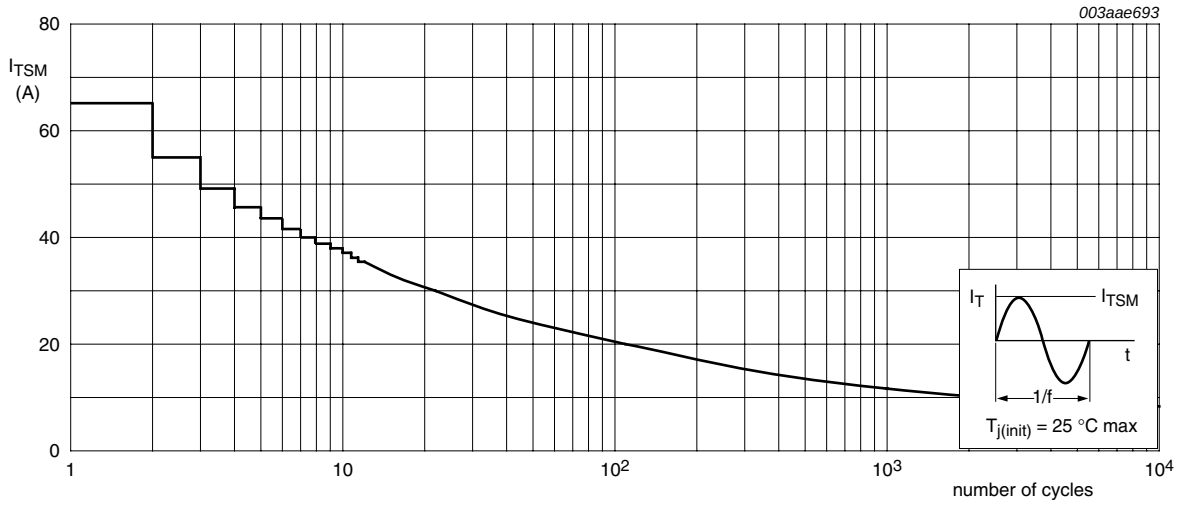


$t_p \leq 20$ ms

(1) dI_T/dt limit

(2) T2- G+ quadrant limit

Fig 4. Non-repetitive peak on-state current as a function of pulse width; maximum values



f = 50 Hz

Fig 5. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	half cycle; see Figure 6	-	-	2.4	K/W
		full cycle; see Figure 6	-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	PCB (FR4) mounted; minimum pad sizes	-	75	-	K/W

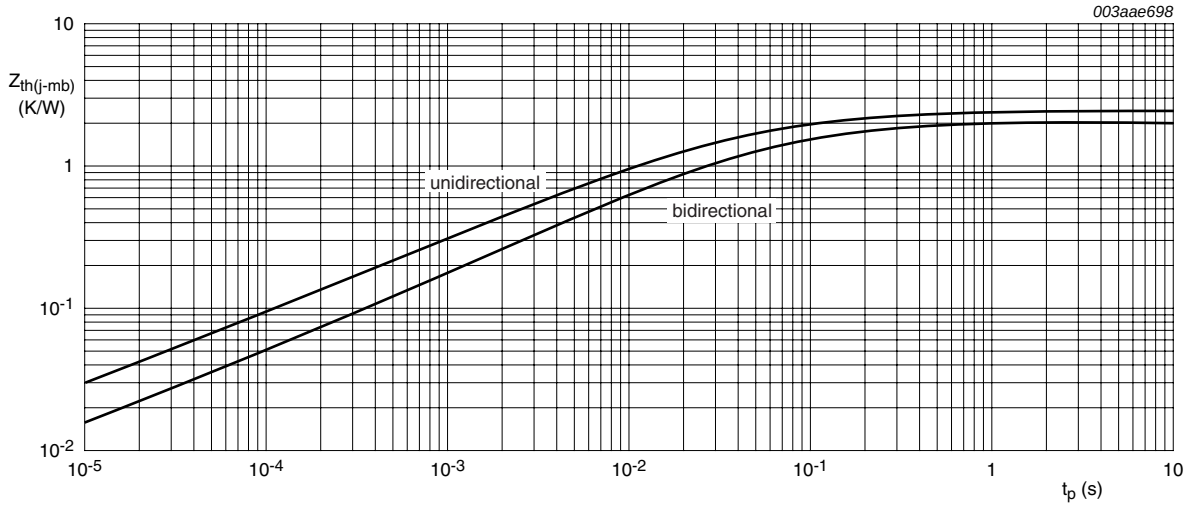
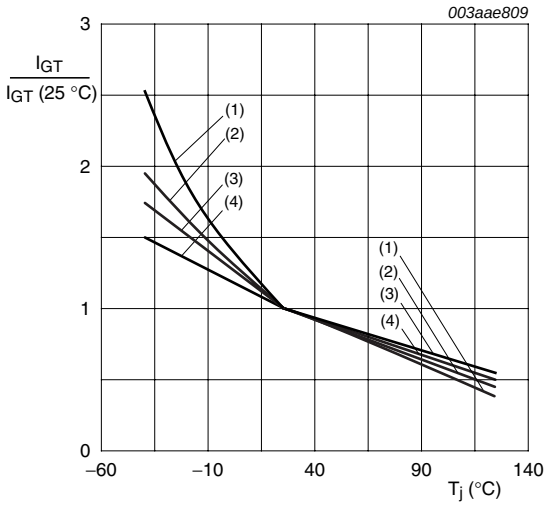


Fig 6. Transient thermal impedance from junction to mounting base as a function of pulse width

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T2+ G+; T_j = 25 °C; see Figure 7	-	2.5	10	mA
		V_D = 12 V; I_T = 0.1 A; T2+ G-; T_j = 25 °C; see Figure 7	-	4	10	mA
		V_D = 12 V; I_T = 0.1 A; T2- G-; T_j = 25 °C; see Figure 7	-	5	10	mA
		V_D = 12 V; I_T = 0.1 A; T2- G+; T_j = 25 °C; see Figure 7	-	11	25	mA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T2+ G+; T_j = 25 °C; see Figure 8	-	3	25	mA
		V_D = 12 V; I_G = 0.1 A; T2+ G-; T_j = 25 °C; see Figure 8	-	14	35	mA
		V_D = 12 V; I_G = 0.1 A; T2- G-; T_j = 25 °C; see Figure 8	-	3	25	mA
		V_D = 12 V; I_G = 0.1 A; T2- G+; T_j = 25 °C; see Figure 8	-	4	35	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; see Figure 9	-	2.5	20	mA
V_T	on-state voltage	I_T = 10 A; T_j = 25 °C; see Figure 10	-	1.3	1.65	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; see Figure 11	-	0.7	1.5	V
		V_D = 400 V; I_T = 0.1 A; T_j = 125 °C; see Figure 11	0.25	0.4	-	V
I_D	off-state current	V_D = 800 V; T_j = 125 °C	-	0.1	0.5	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 536 V; T_j = 125 °C; exponential waveform; gate open circuit	-	50	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 12 A; V_D = 800 V; I_G = 0.1 mA; dI_G/dt = 5 A/µs	-	2	-	µs



(1) T2- G+

(2) T2- G-

(3) T2+ G-

(4) T2+ G+

Fig 7. Normalized gate trigger current as a function of junction temperature

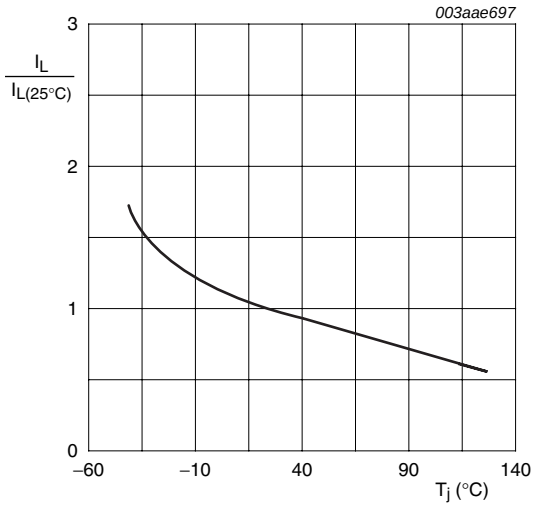


Fig 8. Normalized latching current as a function of junction temperature

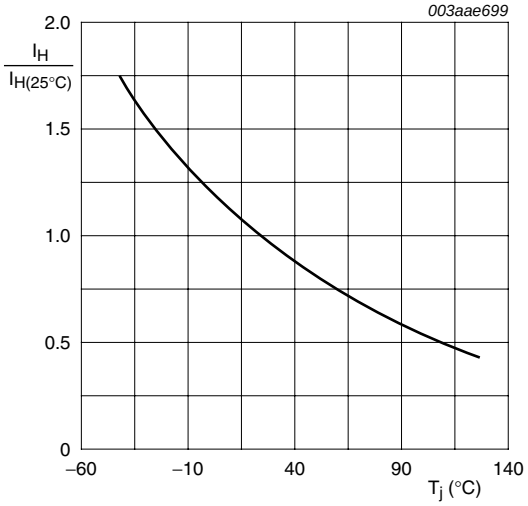
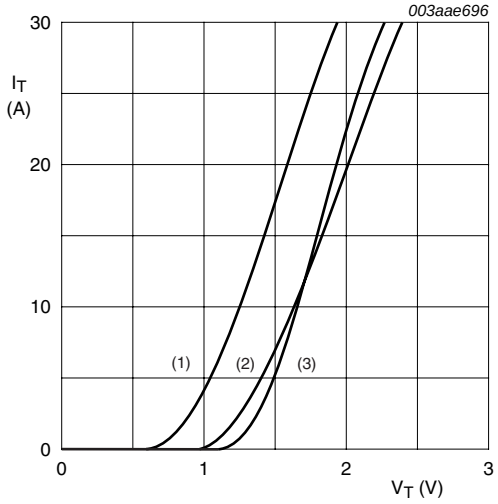


Fig 9. Normalized holding current as a function of junction temperature



V_o = 1.264 V

R_s = 0.038 Ω

(1) T_j = 125 ℃; typical values

(2) T_j = 125 ℃; maximum values

(3) T_j = 25 ℃; maximum values

Fig 10. On-state current as a function of on-state voltage

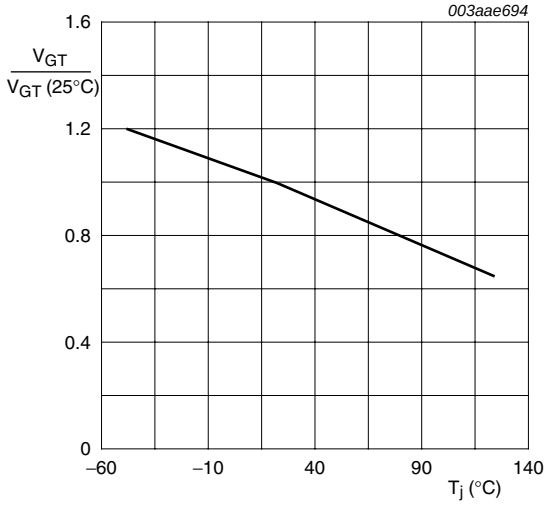
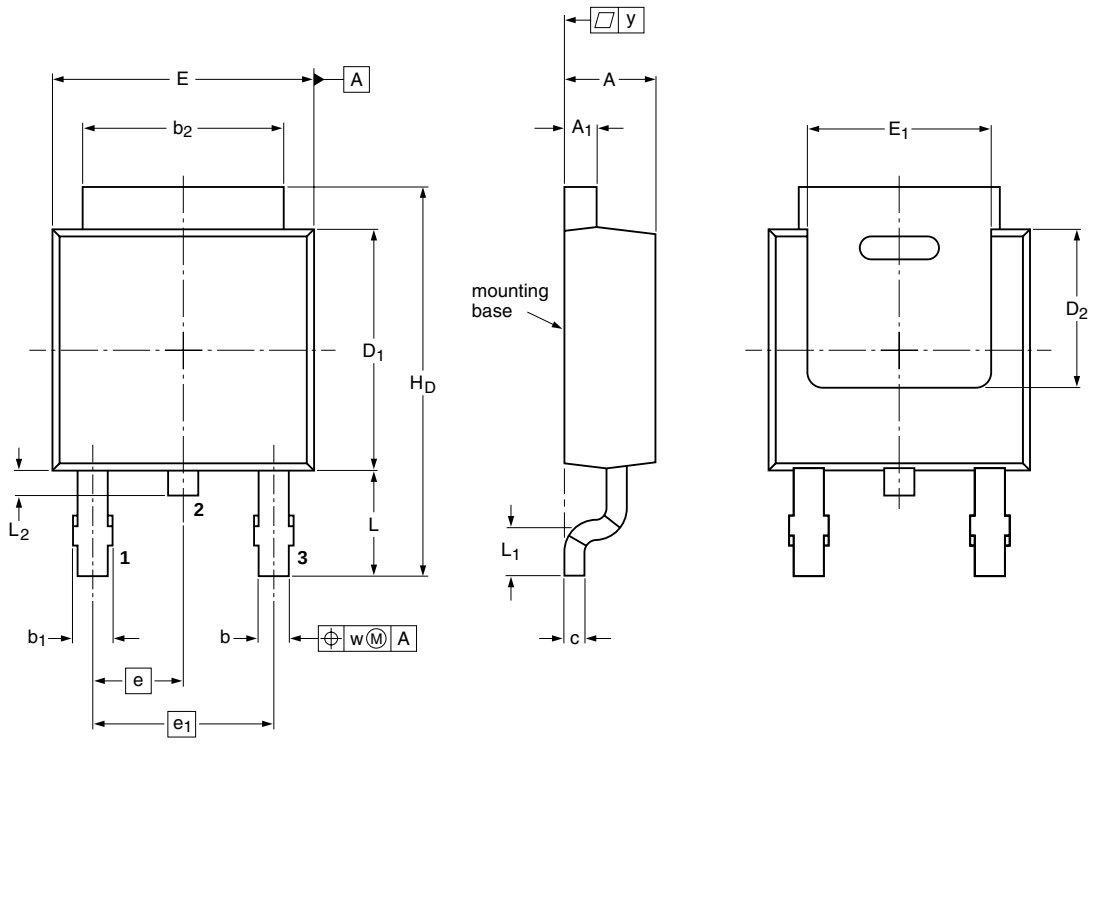


Fig 11. Normalized gate trigger voltage as a function of junction temperature

7. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) **SOT428**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	b_1	b_2	c	D_1	D_2 min	E	E_1 min	e	e_1	H_D	L	L_1 min	L_2	w	y max
mm	2.38 2.22	0.93 0.46	0.89 0.71	1.1 0.9	5.46 5.00	0.56 0.20	6.22 5.98	4.0	6.73 6.47	4.45	2.285	4.57	10.4 9.6	2.95 2.55	0.5	0.9 0.5	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT428		TO-252	SC-63			~~06-02-14~~ 06-03-16

Fig 12. Package outline SOT428 (DPAK)

8. Soldering

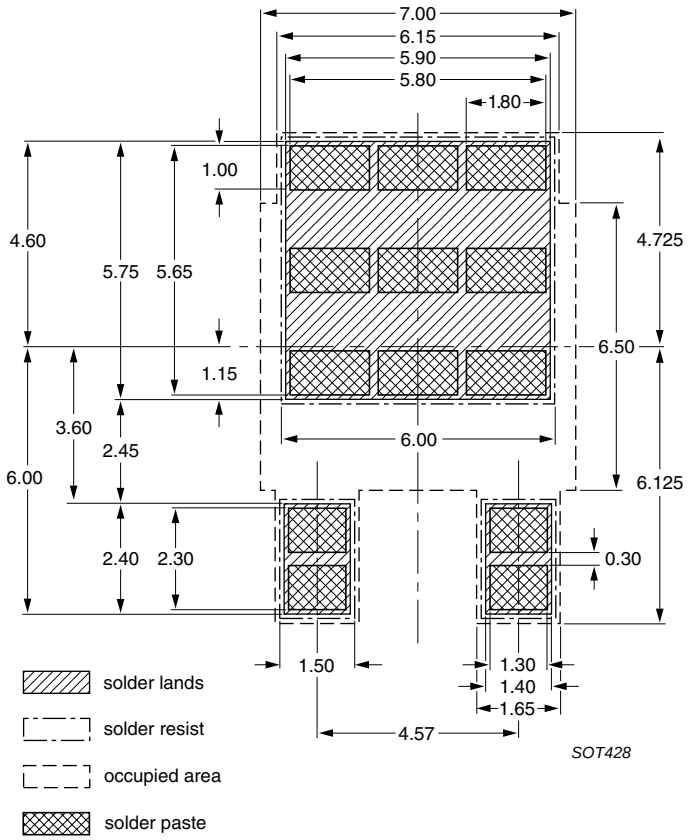


Fig 13. Reflow soldering footprint for SOT428 (DPAK)

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BT137S-800E v.3	20110330	Product data sheet	-	BT137S_SERIES_E_2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Type number BT137S-800E separated from data sheet BT137S_SERIES_E_2.			
BT137S_SERIES_E_2	20010601	Product specification	-	BT137S_SERIES_E_1

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10.1 Data sheet status

Document status [1] [2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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12. Contents

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